

IN THE ABSTRACT:

Please enter the attached substitute Abstract of the Disclosure for that originally filed with this application.

ABSTRACT OF THE DISCLOSURE

In manufacturing a multi-layer printed circuit board (PCB), different processes are employed for forming inner and outer circuit layers of the PCB. Particularly, second and third inner circuit layers of the multi-layer PCB are formed with the resin build-up process through liquid epoxy coating or dry film type epoxy laminating to enable refinement of circuits provided thereon, and two outer circuit layers of the multi-layer PCB are formed on copper clad and insulating dielectric with a lamination process.